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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HSB0104YP

Silicon Schottky Barrier Diode for High Speed Switching

ADE-208-730A (Z)

Rev. 1
Sep. 2000

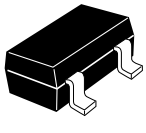
Features

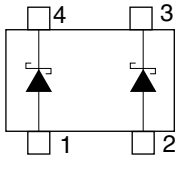
- Can be used for protection of signal-bus lines.
- The mounting efficiency has been improved by incorporating two low-loss diode element into a CMPAK-4 package.

Ordering Information

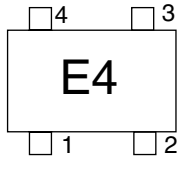
Type No.	Laser Mark	Package Code
HSB0104YP	E4	CMPAK-4

Pin Arrangement





(Top View)



(Top View)

1 Anode
2 Anode
3 Cathode
4 Cathode

Absolute Maximum Ratings *[1]

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse peak reverse voltage	V_{RRM}	40	V
Forward current	I_F	100	mA
Non-Repetitive peak forward surge current	I_{FSM} *[2]	3	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Notes: 1. Per one device.
2. 10ms sine wave 1 pulse.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	0.58	V	I_F = 100 mA
Reverse current	I_R	—	—	50	μA	V_R = 40 V
Capacitance	C	—	20	—	pF	V_R = 0 V, f = 1 MHz

Main Characteristic

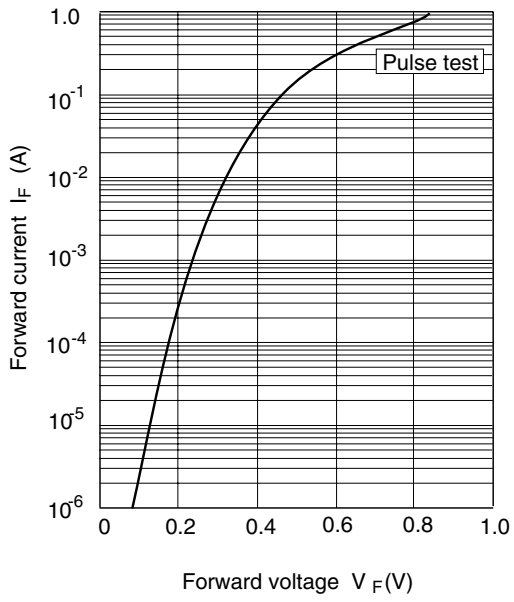


Fig.1 Forward current Vs. Forward voltage

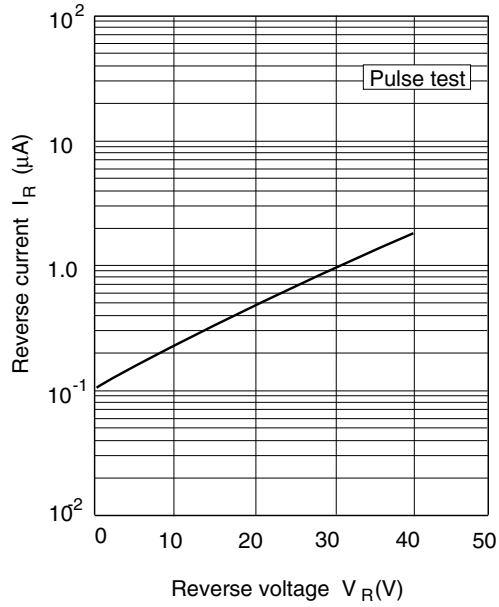


Fig.2 Reverse current Vs. Reverse voltage

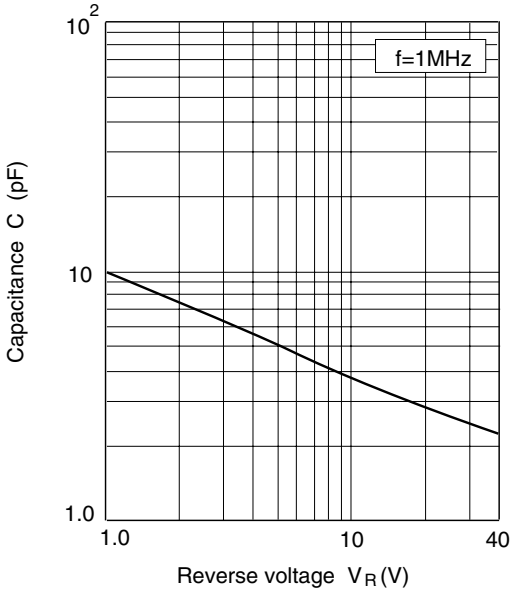
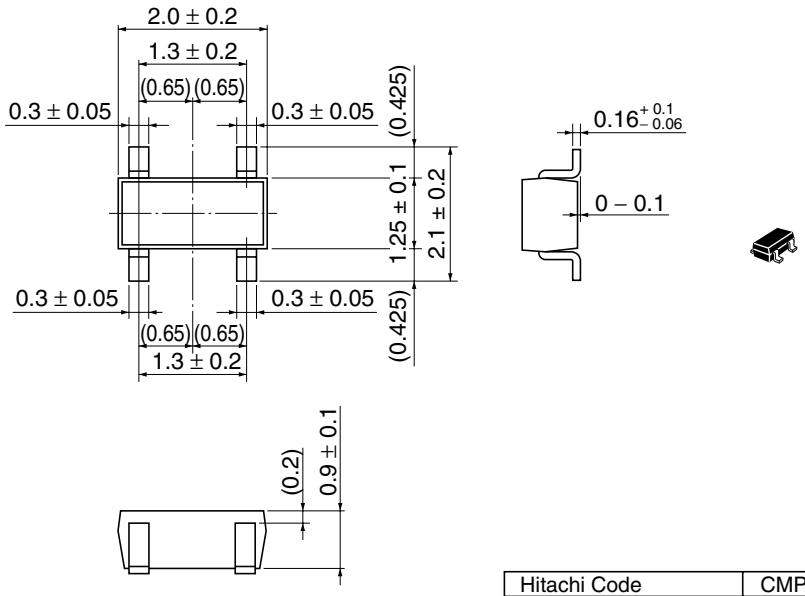


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



Hitachi Code	CMPAK-4(D)
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.006 g

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